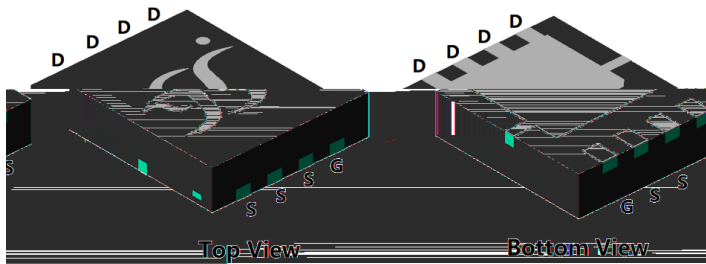


P-Channel Enhancement Mode Field Effect Transistor



Product Summary

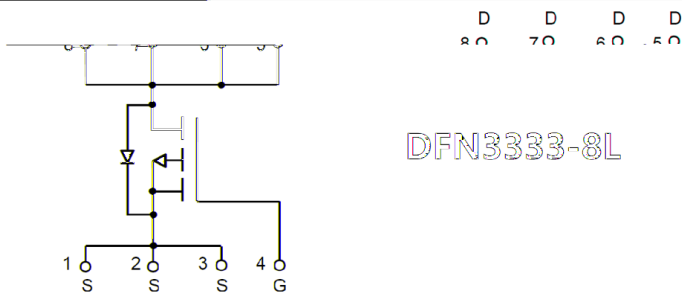
V_{DS}	-30 V
I_D	-40 A
$R_{DS(ON)}$ (at $V_{GS}=-10V$)	12 m
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$)	16 m
100% EAS Tested	

General Description

Trench Power LV MOSFET technology
 Low $R_{DS(on)}$ & FOM
 Extremely low switching loss
 Excellent stability and uniformity
 : $V_a R R \sqrt{V} 9R RY$
 Epoxy Meets UL 94 V-0 Flammability Rating
 Halogen Free

Applications

= R ZN NTRZR a
 = aNORR VZR a



Absolute Maximum Ratings ($T_A=25$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	-30	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_A=25^\circ C$	I_D	-12	A
	$T_A=100^\circ C$		-7.5	
	$T_C=25^\circ C$		-40	
	$T_C=100^\circ C$		-25	
Pulsed Drain Current ^A		I_{DM}	-140	A
Avalanche energy ^B		EAS	98	mJ
Total Power Dissipation ^C	$T_A=25^\circ C$	P_D	2	W
	$T_A=100^\circ C$		0.8	
	$T_C=25^\circ C$		50	
	$T_C=100^\circ C$		20	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 +150	$^\circ C$

Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^D	Steady-State	$R_{\theta J}$	50	60	$^\circ C/W$
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	2	2.5	

Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJQ40P03AJ	F1	Q40P03AJ	5000	10000	100000	13 reel



YJQ40P03AJ

Electrical Characteristics ($T_J=25$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-$	-30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-30V, V_{GS}=0V$	-	-	-1	.
		$V_{DS}=-30V, V_{GS}=0V, T_J=150^{\circ}C$	-	-	-100	
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-$	-1	-1.5	-2	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-20A$	-	9	12	Z
		$V_{GS}=-4.5V, I_D=-10A$	-	12	16	
Diode Forward Voltage	V_{SD}	$I_S=-20A, V_{GS}=0V$	-	-	-1.2	V
Gate resistance	R_G	$f=1MHz, \text{Open drain}$	-	4.5	-	
Maximum Body-Diode Continuous Current	I_S		-	-	-40	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=-15V, V_{GS}=0V, f=1MHz$	-	1800	-	pF
Output Capacitance	C_{oss}		-	240	-	
Reverse Transfer Capacitance	C_{rss}		-	230	-	
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=-10V, V_{DS}=-15V, I_D=-20A$	-	37	-	nC
Gate-Source Charge	Q_{gs}		-	6	-	
Gate-Drain Charge	Q_{gd}		-	8	-	
Reverse Recovery Charge	Q_{rr}	$I_F=-20A, di/dt=100A/us$	-	1.5	-	nC
Reverse Recovery Time	t_{rr}		-	13	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=-10V, V_{DD}=-15V, I_D=-20A$ $R_{GEN}=3$	-	9	-	ns
Turn-on Rise Time	t_r		-	56	-	
Turn-off Delay Time	$t_{D(off)}$		-	45	-	
Turn-off fall Time	t_f		-	78	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B. $T_J=25^{\circ}C, V_{DD}=-30V, V_G=-10V, R_G=9\ 1mH, I_{AS}=-14A$.

C. P_d is based on max. junction temperature, using junction-case and junction-ambient thermal resistance.

D. The value of R_{θ} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in the still air environment with $T_A=25^{\circ}C$.

The maximum allowed junction temperature of 150. The value in any given application depends on the user's specific board design.



Typical Electrical and Thermal Characteristics Diagrams

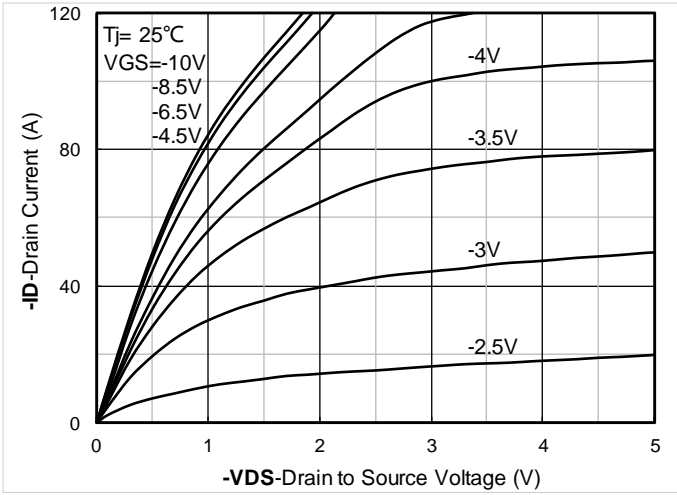


Figure 1. Output Characteristics

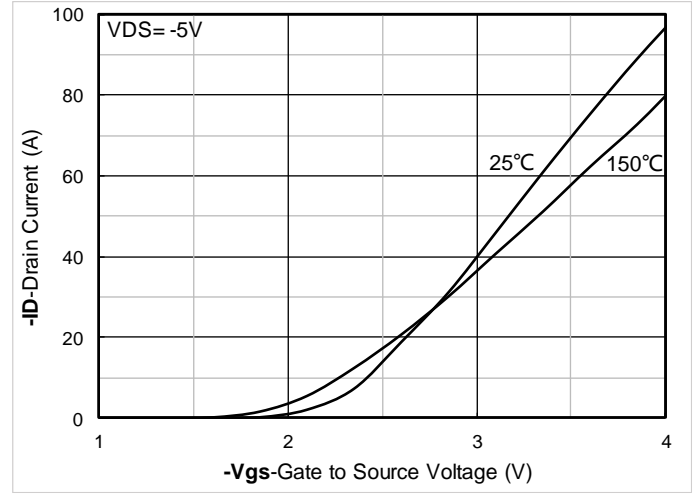


Figure 2. Transfer Characteristics

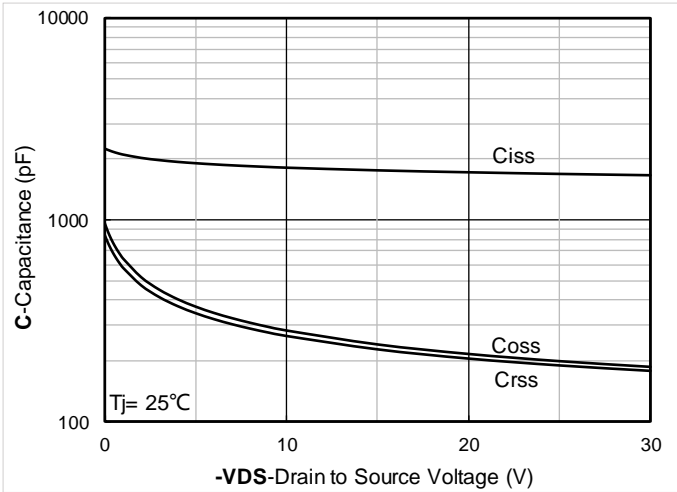


Figure 3. Capacitance Characteristics

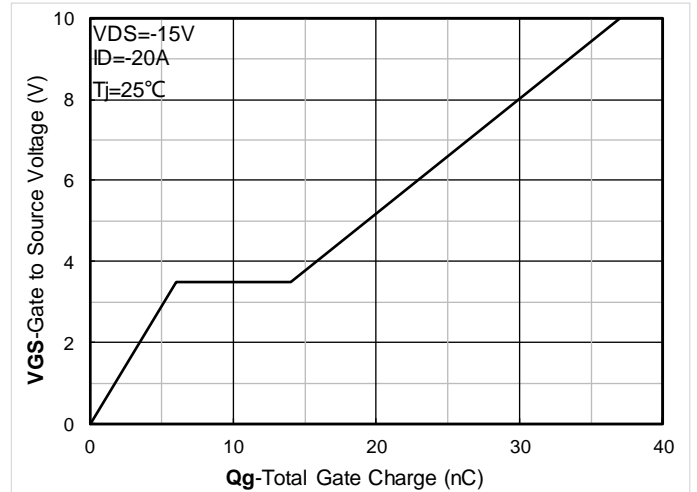


Figure 4. Gate Charge

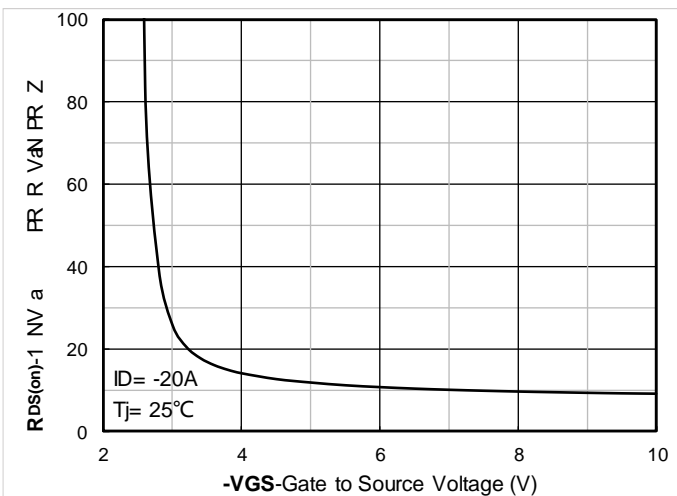


Figure 5. On-Resistance vs Gate to Source Voltage

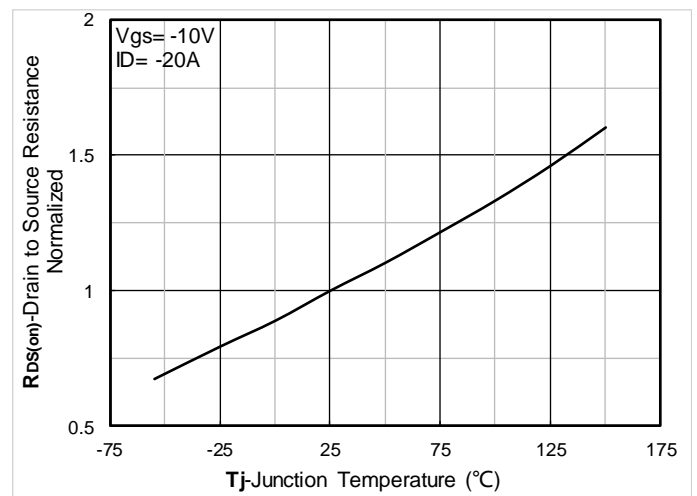


Figure 6. Normalized On-Resistance



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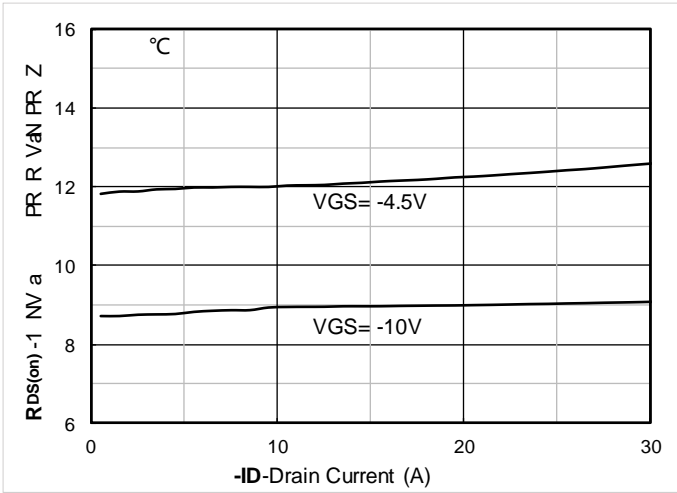


Figure 7. RDS(on) VS Drain Current

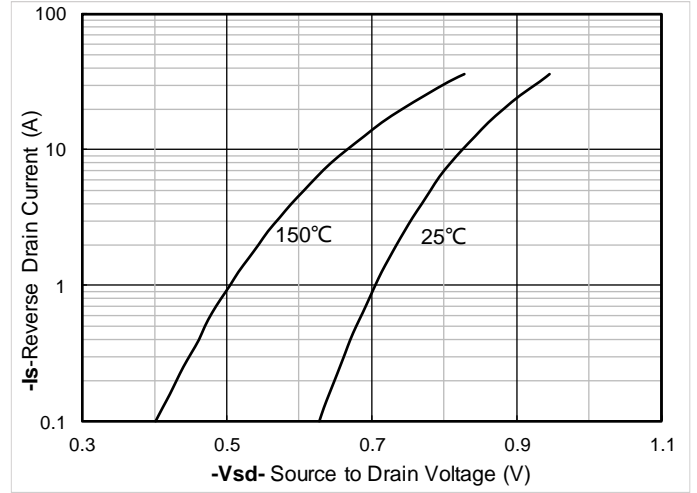


Figure 8. Forward characteristics of reverse diode

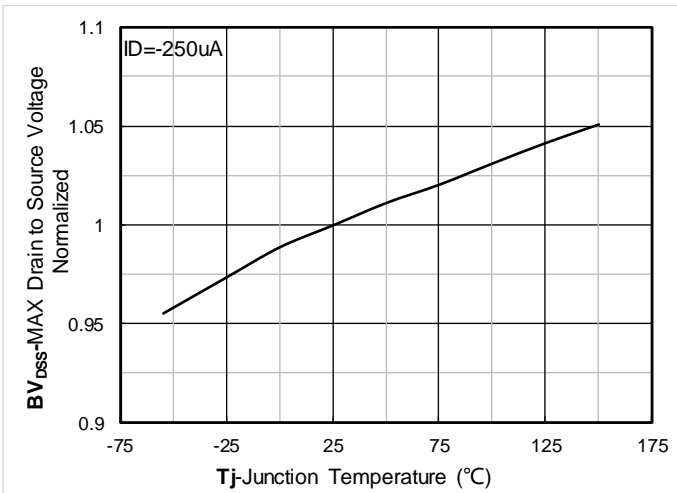


Figure 9. Normalized breakdown voltage

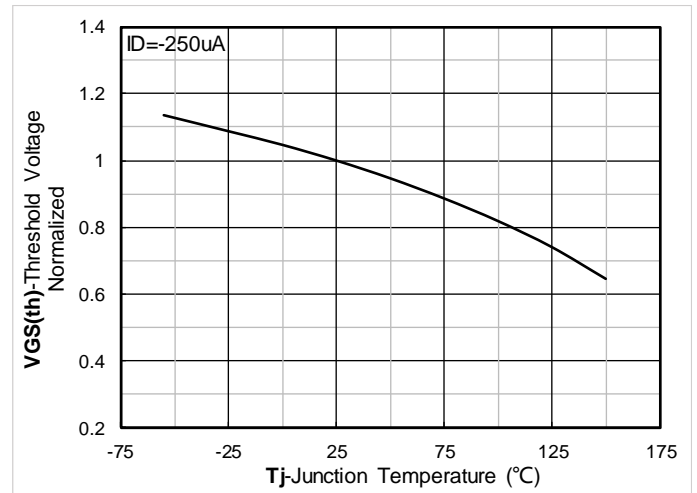


Figure 10. Normalized Threshold voltage

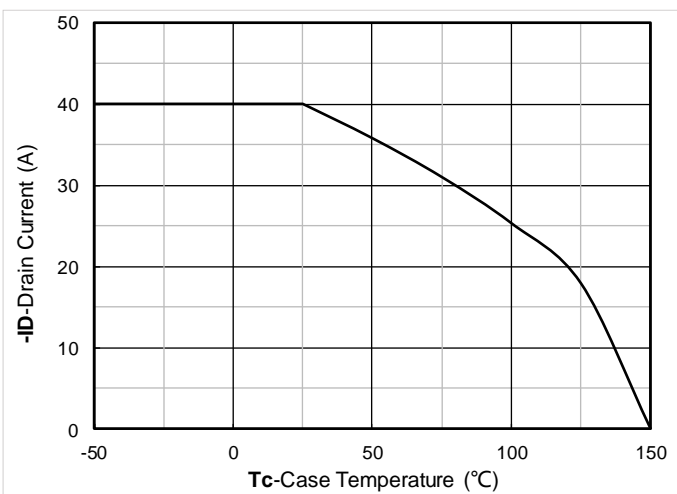


Figure 11. Current dissipation

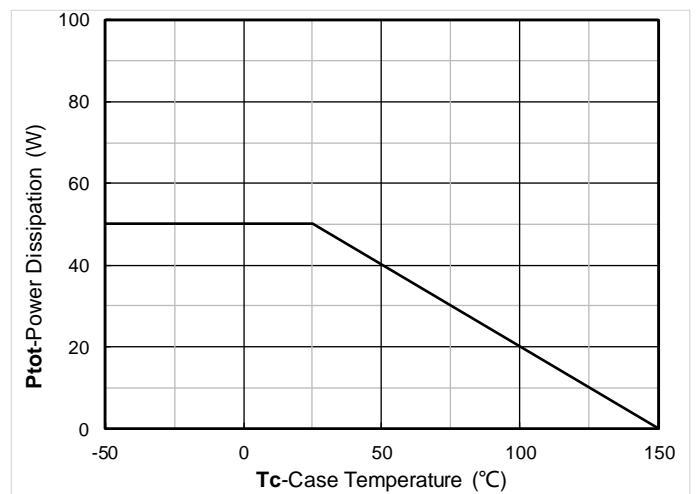


Figure 12. Power dissipation



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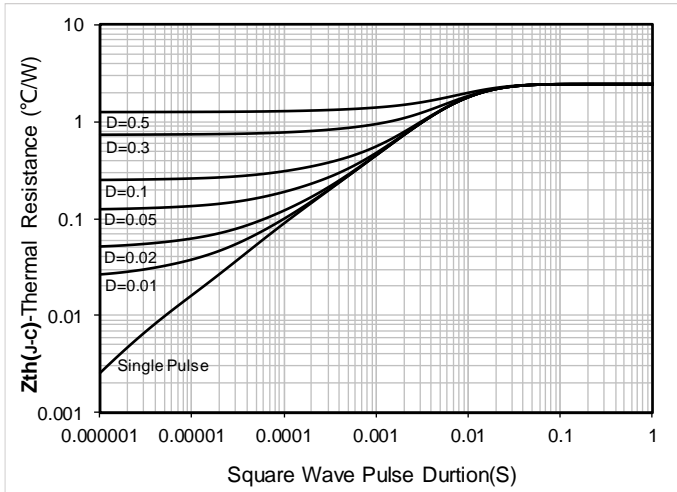


Figure 13. Maximum Transient Thermal Impedance

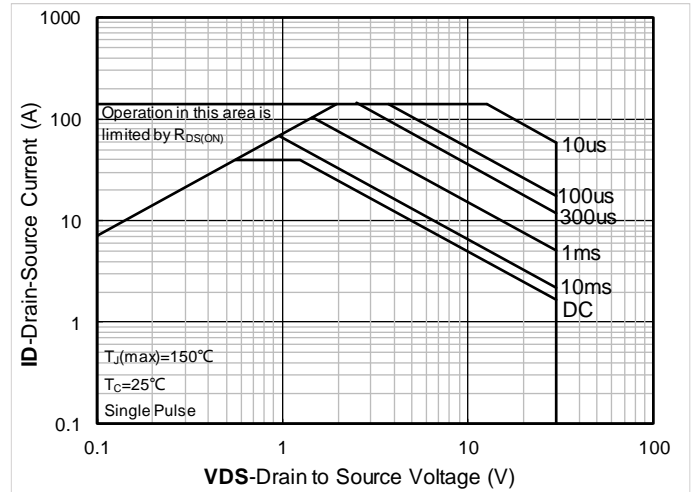
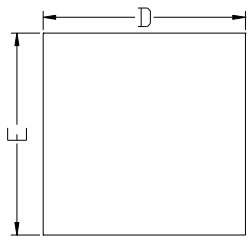


Figure 14. Safe Operation Area

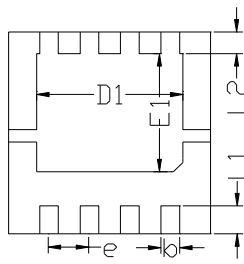


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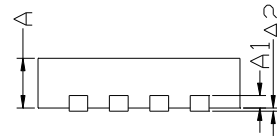
DFN3333-8L Package information



Top View

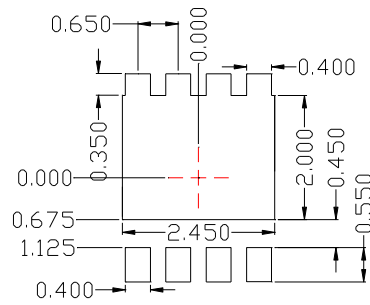


Bottom View



Side View

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	3.15	3.25	3.35
E	3.15	3.25	3.35
A	0.70	0.80	0.90
A1	0.20 BSC		
A2			0.10
D1	2.20	2.35	2.50
E1	1.80	1.90	2.00
L1	0.35	0.45	0.55
L2	0.35 BSC		
b	0.20	0.30	0.40
e	0.65 BSC		



Suggested Solder Pad Layout
Top View

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.10 mm.
3. The pad layout is for reference purposes only.



YJQ40P03AJ

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